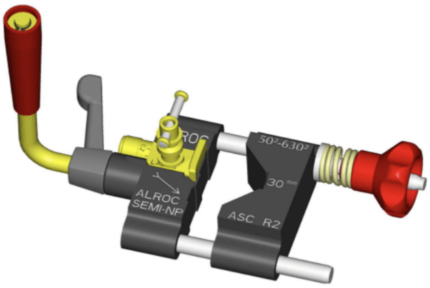
# / ASC R1

Tools for bonded semiconductor and chamfer

See online
technical sheet



## / Use

ASC tools allow the removal of the non-peelable semiconductor with the creation of a chamfer and a very correct surface finish.

## / Advantages

- Robust design
- Lightweight
- Easy to get to grips with

## / Technical specifications

- **Specific tools :** Cable tools
- **Cable tools :** Cable tools
- **For network cables :** HTA
- **Packaging :** Carton box
- **Width (mm) :** 110
- **Height (mm) :** 135
- **Max diameter (mm) :** 40
- **Mini diameter (mm) :** 14
- **Incision depth on semi-peelable material :** 0,1 à 1,4 mm
- **Lenght (mm) :** 205
- **Weight (g) :** 620

## / Spare parts

| | Reference | Designation |
|---|---|---|
|  | **LASCR1** | Blade for bonded semiconductor |